

Brazing explosively bonded Nb-Cu to Alumina Ceramic

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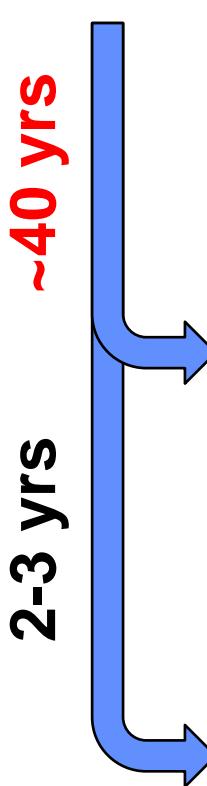
Outline – brazing explosively bonded Nb/Cu

- Overview: Why this material set?
 - Switch processing methods:
current, development, future
- Nb- Al_2O_3 material properties
- Brazing experiments
 - Overview, processing, testing results
- Conclusions & path forward



Why the interest? Switch processing methods

Why the interest?



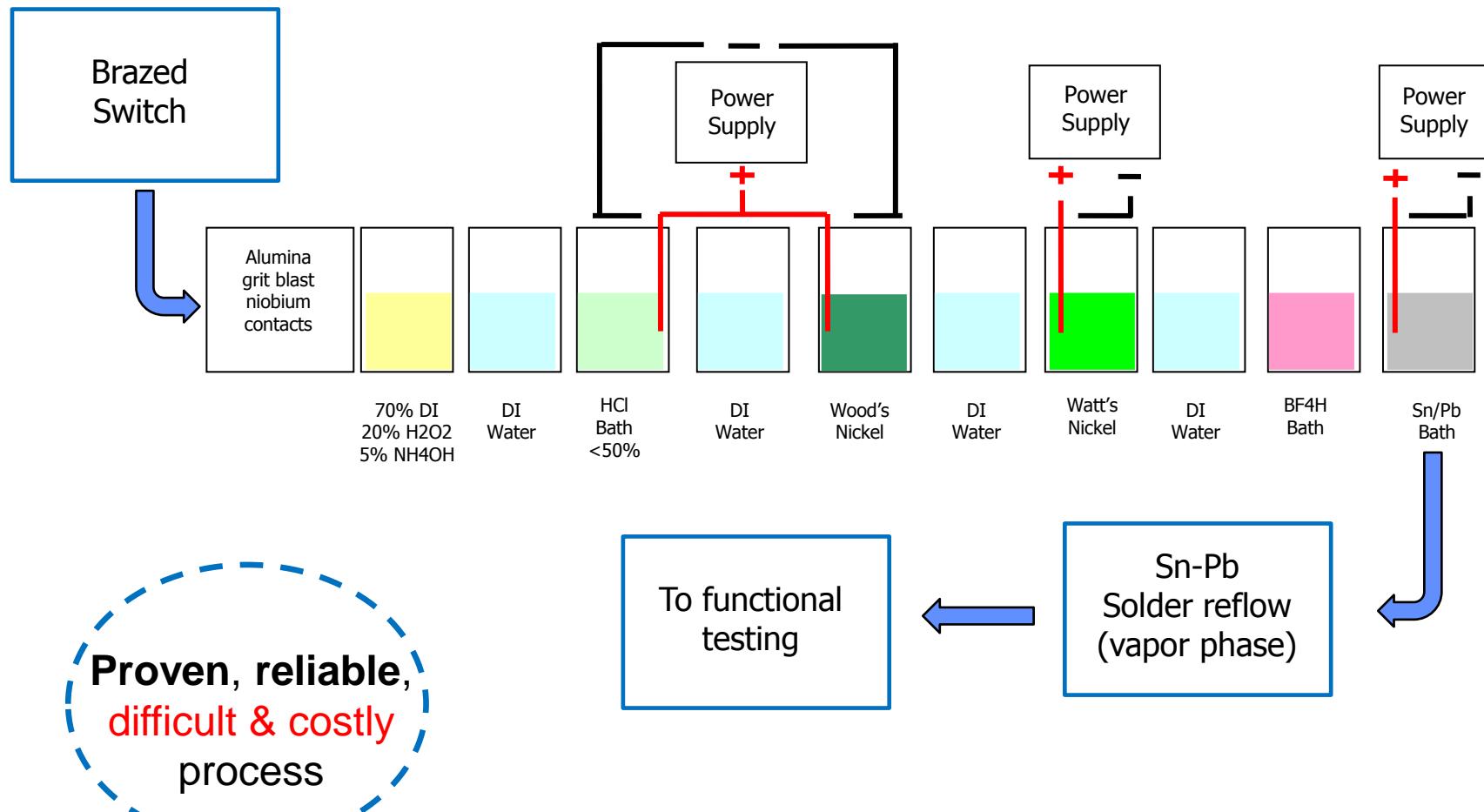
Currently used switch production process:
Braze, Ni/Sn-Pb plate, Reflow solder, Test. (\$\$\$)

Development switch process:
Braze, Rebraze, Solder Dip, Test (\$\$)

Future switch process:
Braze, Solder Dip, Test (\$)



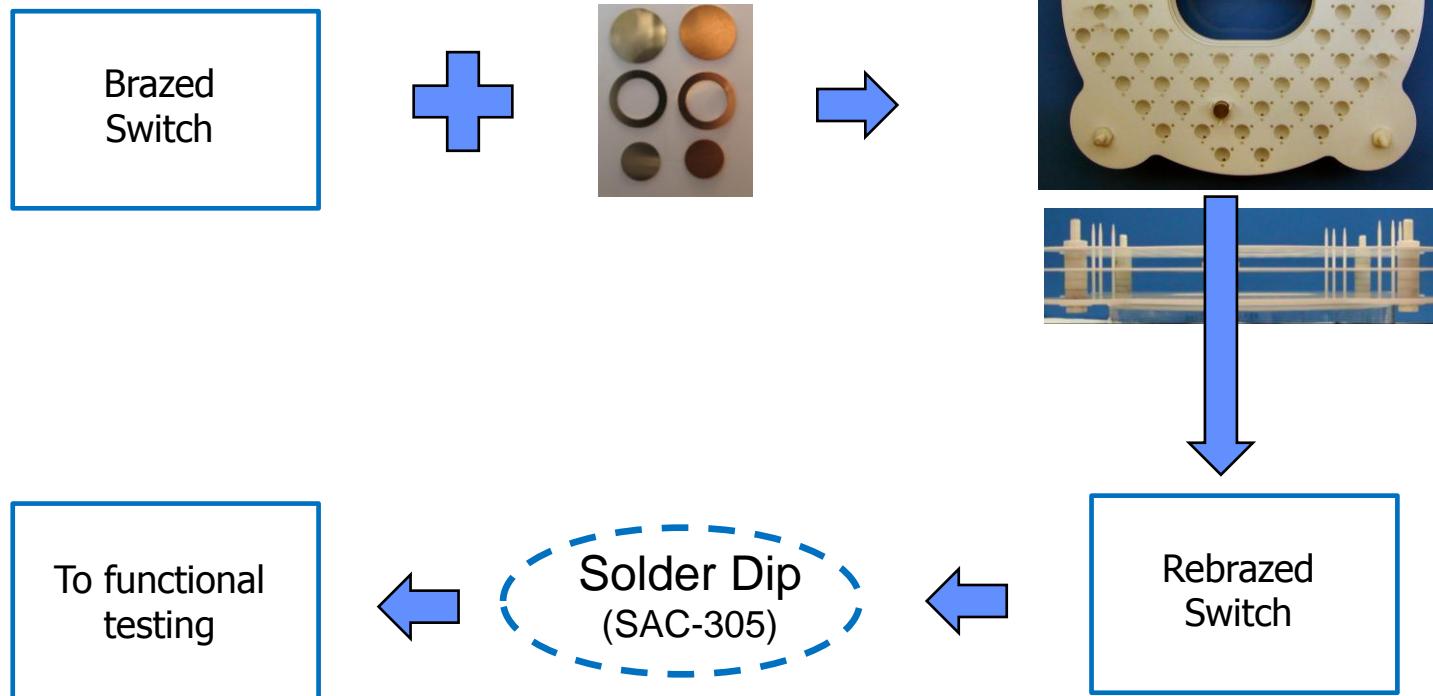
Current production post-braze processing





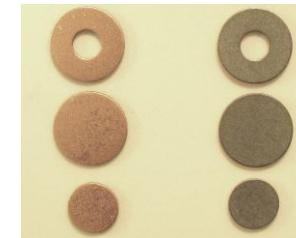
Development - step-brazing & solder dipping copper contacts

Refixture and furnace step-braze
copper switch contacts





Future production: solder dipping explosively bonded Nb-Cu contacts



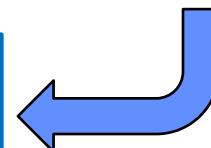
Explosively bonded
Nb-Cu contacts

One fixturing step, one braze process



Successfully
demonstrated
Q3 2011!!

To functional
testing





Summary Table: three methods of switch fabrication

Switch fabrication method	Pros	Cons
Standard (Ni/Sn-Pb plate, reflow)	<ul style="list-style-type: none">• 1-step brazing process• Proven method• Works well	<ul style="list-style-type: none">• Expensive• Time-consuming• Complex plating process
2-Step braze method	<ul style="list-style-type: none">• Eliminates plating/reflow• Compatible with Pb-free solder-dipping processes• Works well.	<ul style="list-style-type: none">• Refixturing required• 2-step brazing process• Additional parts• Additional risk
Braze using explosively bonded Nb-Cu	<ul style="list-style-type: none">• 1-step brazing process• Compatible with Pb-free solder-dipping processes• Same part count as standard method.	<ul style="list-style-type: none">• Unproven method• CTE mismatch in bonded material• Unknown Nb-Cu bond interlayer strength• ?



Resultant stresses due to CTE mismatch

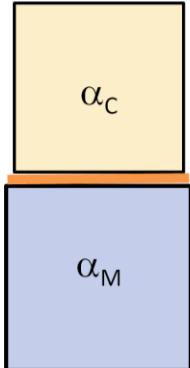
CTE Metal > CTE Ceramic, ($\alpha_M > \alpha_c$)

Unconstrained Substrates

Room Temperature

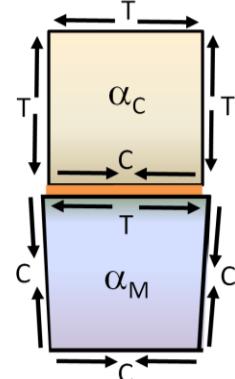


Joining Temperature



Constrained Substrates

Post-Joining,
Room Temperature



α_c = CTE Ceramic, α_M = CTE Metal

T = Tension, C = Compression,

 = Ceramic Substrate

 = Metal Substrate

 = Braze Filler Metal

 = Stress Direction

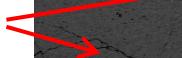
Resultant stresses when
brazing dissimilar materials

Sometimes the
metal deforms

Kovar brazed to
94% alumina



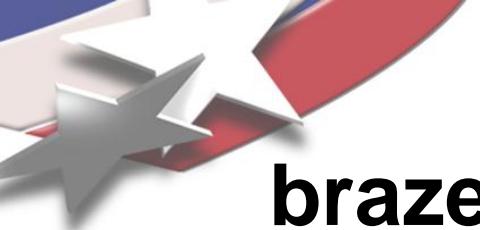
zirconia



tungsten carbide



EHT = 15.00 kV WD = 10.6 mm Signal A = BSD File Name = 080510-1_01.tif



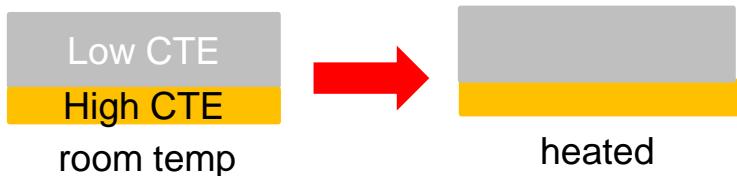
Selected substrate and braze filler metal material properties

Material	Coefficient of Thermal Expansion (linear, 20-1000°C, *10 ⁻⁶ /°C)	Ultimate Tensile Strength / Elongation at Break	Compressive Strength
94% Al ₂ O ₃	7.4	138 MPa (20 ksi)	1931 MPa (280 ksi)
Sapphire	6.7	400 MPa (58 ksi)	2930 MPa (425 ksi)
Niobium (commercially pure)	8.4	300 MPa (43.5 ksi)/30%	----
Kovar	11.3	517 MPa (75 ksi)/30%	----
Copper	25	210 MPa (31 ksi)/60%	----
BAu-3 (Nicoro™)	17.8	427 MPa (62 ksi)/28%	----
Nicoro™+2%Ti	17.8 (est.)	427 MPa (62 ksi)/28% (est.)	----

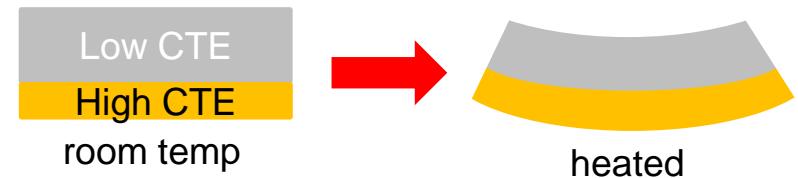


Bi-metallic strip behavior

Typical behavior *unconstrained*



Typical behavior *constrained*

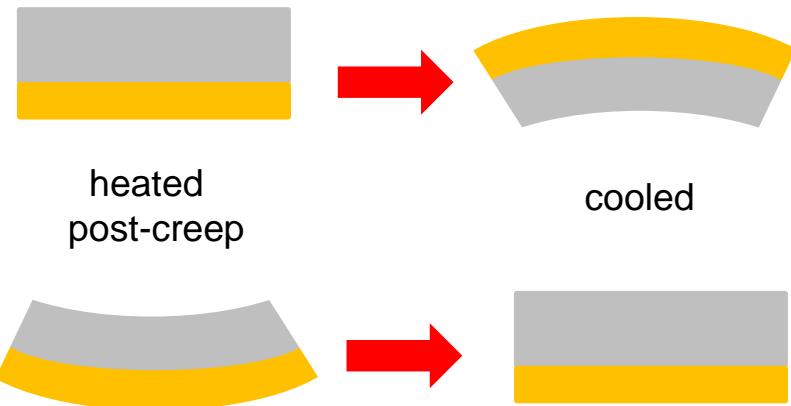


Expected Behavior

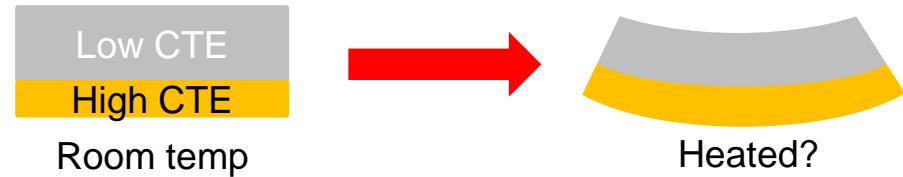


Path 1

Path 2

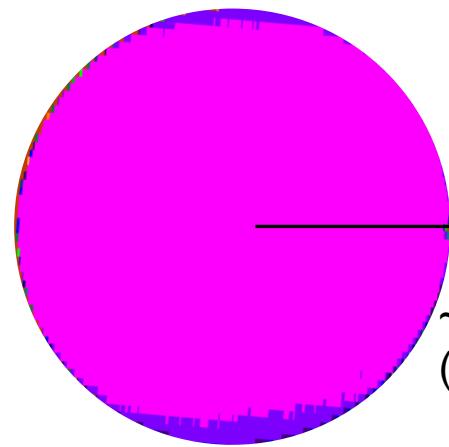


Observed Behavior



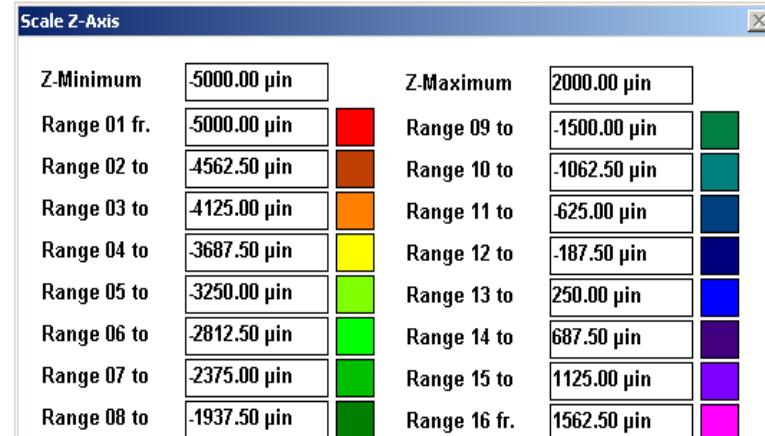
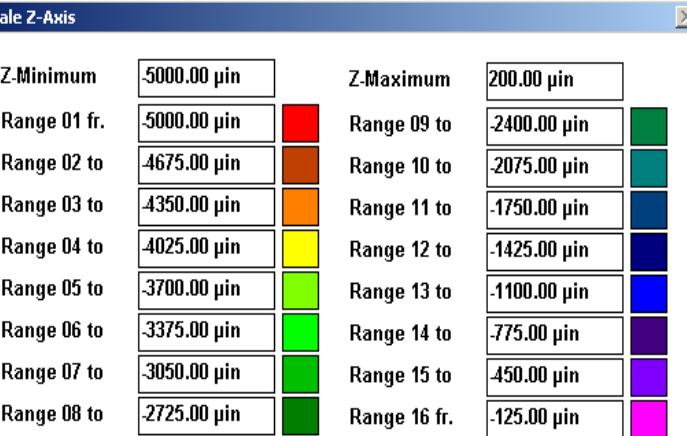
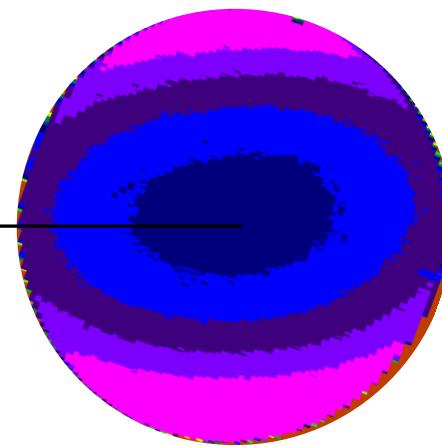
Measured warp: 7.92mm diameter Nb disc #A1

As-Received



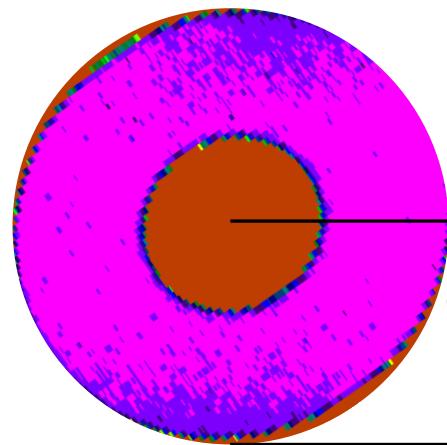
↑
~0.000325"
(0.0083mm)
↓

Post-Clean & Vac Bake

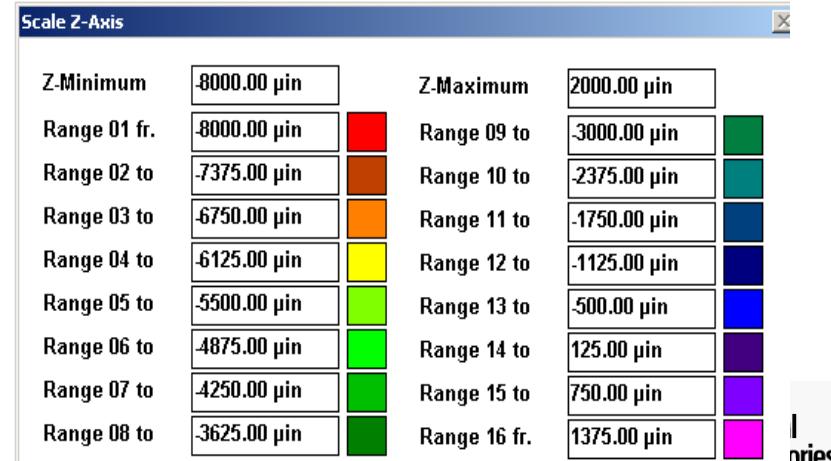
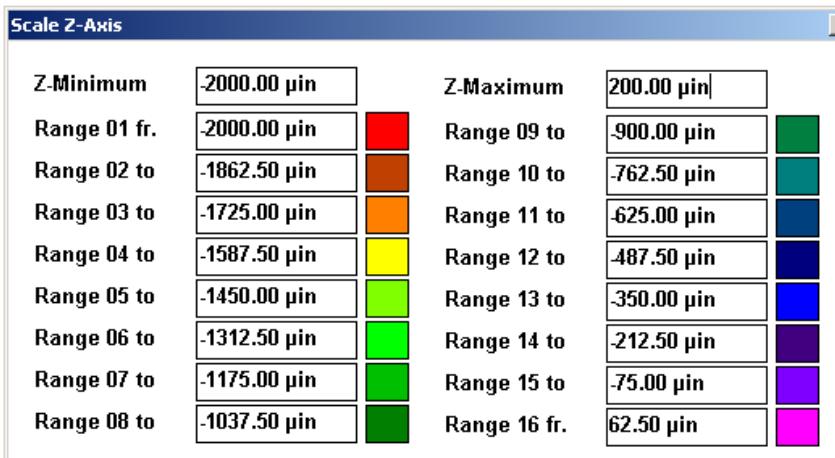
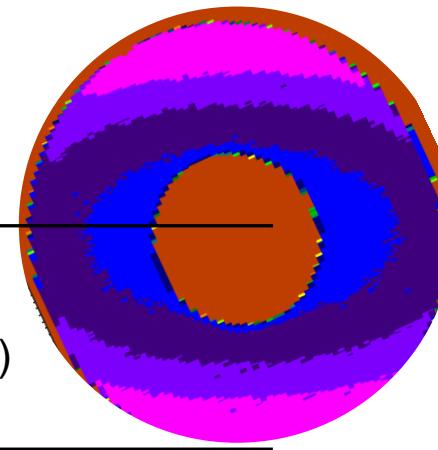


Measured warp: 7.92mm OD x 3.10mm ID Nb washer #B2

As-Received

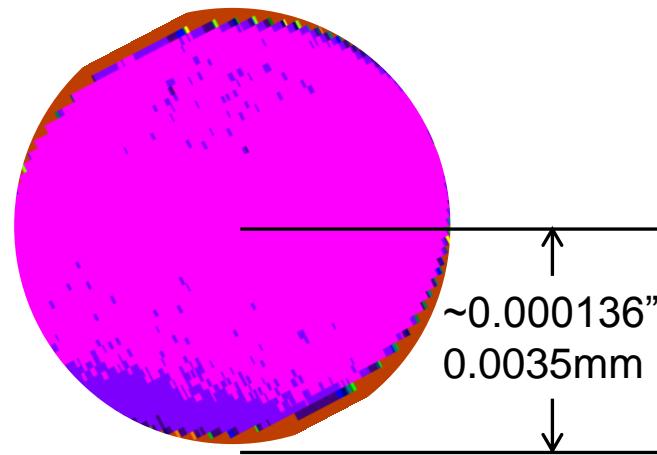


Post-Clean & Vac Bake

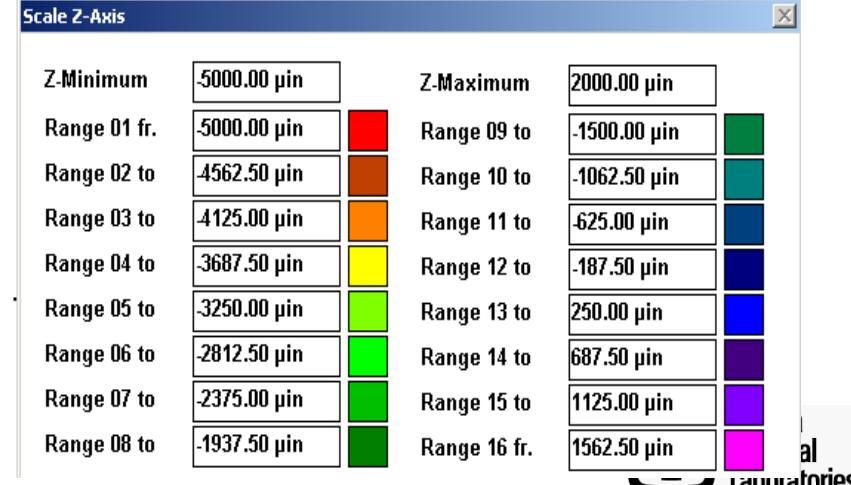
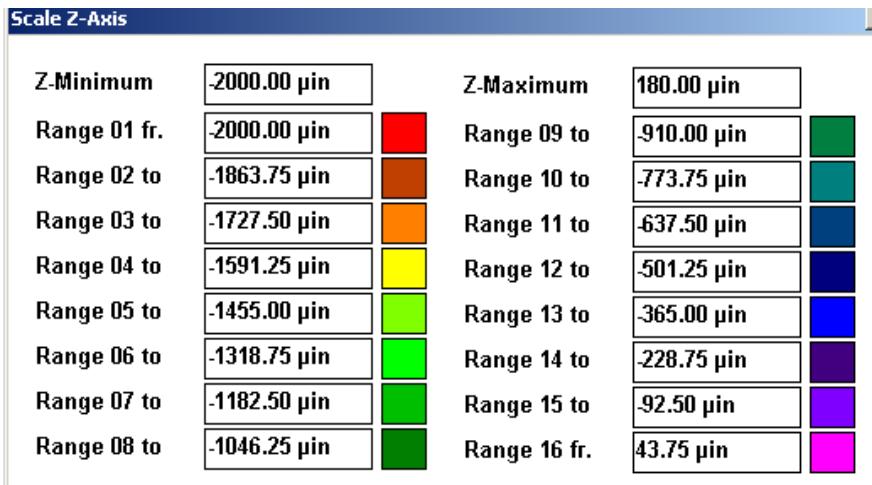
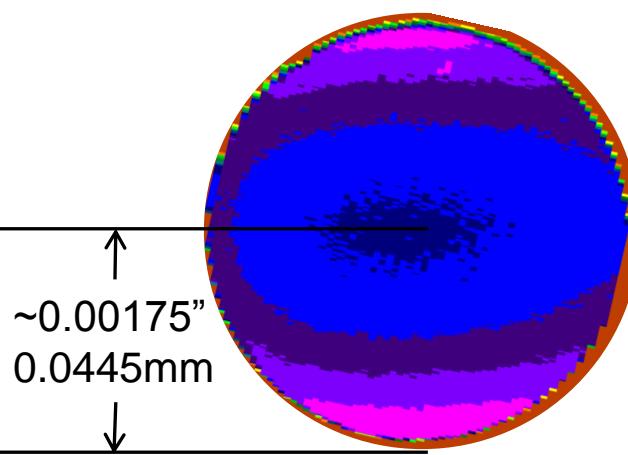


Measured warp: 5.44mm diameter Nb disc – #C4

As-Received



Post-Clean & Vac Bake





Thermal-cycled Nb-Cu substrate behavior

Item	OD	Pre-bake flatness	Post-bake flatness	Average difference	Std. Dev
Small contact (disc)	5.44 mm 0.214"	0.010 mm 0.0004"	0.046 mm 0.0018"	0.036 mm 0.0014"	0.010 mm 0.0004"
Medium contact (washer)	7.92 mm 0.312"	0.020 mm 0.0008"	0.056 mm 0.0022"	0.036 mm 0.0014"	0.015 mm 0.0006"
Medium contact (disc)	7.92 mm 0.312"	0.015 mm 0.0006"	0.043 mm 0.0017"	0.028 mm 0.0011"	0.013 mm 0.0005"
Tensile button interlayer (washer)	15.88 mm 0.625"	N/A	N/A	~0.25 mm 0.010"	N/A

Braze joint area comparison:

Switch contacts to tensile button interlayers





Active-brazing explosively bonded Nb-Cu to alumina

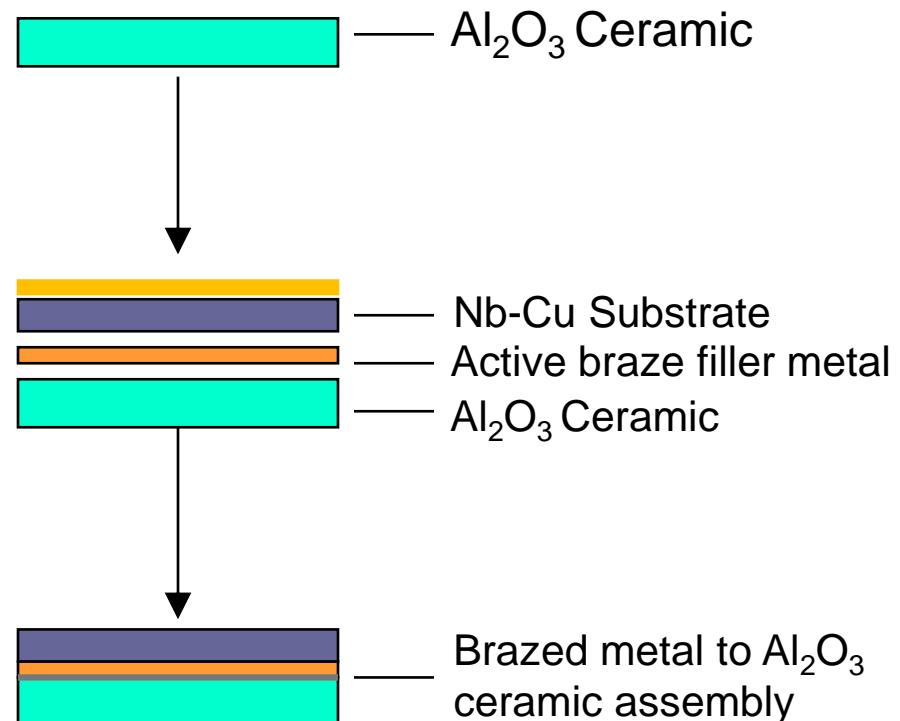
Advantages

- Ease of use
- Variety of filler metal schemes & temperature ranges
- No specialized metallization equipment or processes required
- Easily brazed using standard filler metals

Disadvantages

- Requires specialized equipment/atmosphere control
- Not usable with all joint designs
- Size constraints

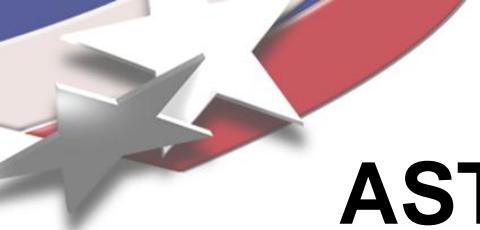
Active filler-metal brazing



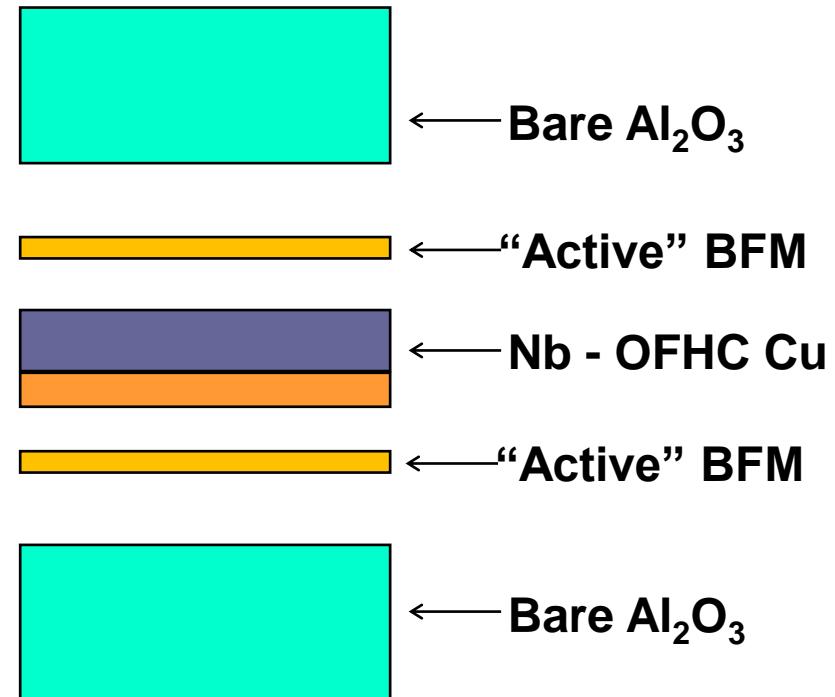


Proposed tensile button experiment

- Fabricate ASTM-F19 tensile button assemblies using bare 94% and 96% alumina with explosively bonded niobium-copper interlayers.
 - Alumina substrates air-fired @ 1575C-2 hours, Nb-Cu interlayers vac-baked @ 1060°C-10 minutes, followed by 800°C-2 hours, flattened.
 - Braze filler metal, Nicoro+2%Ti, BAu-3 (other filler metals in process)
- **Input variables:**
 - Bare alumina composition (94%, 96%), surface finish varied from (28 μ in – 60 μ in)
 - Peak soak temp. (1025°C or 1030°C)
 - Peak soak time (1 or 2 minutes)
 - Control samples (metallized, Mo-Mn/Ni plated 94% alumina tensile buttons)
 - Peak soak temp. (1035°C or 1055°C)
 - Peak soak time (1 minute)
- **Response variables:** tensile strength & hermeticity



ASTM-F19 tensile button geometry



Measured Responses

Tensile strength: MTS crosshead speed = 8.38E-03 mm/sec

Hermeticity : helium leak rates <5E-12 atm-cc/sec desired



Experiment drivers / goals

1. Accommodate design changes in future products with no loss in hermeticity or joint tensile strength.
2. Use slightly lower active brazing process temperatures to minimize excess flow of braze filler metal sometimes observed using the current brazing profile.

T_e Nicoro+2%Ti ~ 1020°C, T_e Nicoro ~ 1030°C

<u>Item</u>	<u>Existing</u>	<u>Proposed</u>
Contact Material:	Pure Niobium	Nb-Cu
T_{PEAK} , Nicoro+2%Ti	1035°C – 1040°C	1025°C-1030°C
T_{PEAK} , Nicoro	1060°C	1035°C-1055°C



Experimental trials

- 36 tensile buttons were made in 6 separate brazing cycles.
 - 6 samples per condition.
 - Tensile strengths are the *average* of 6 samples.
- All samples were made in a modified Brew furnace in UHV atmosphere, 1.3×10^{-3} Pa (1×10^{-6} Torr) at peak temperature. Braze joint preload was 47g/cm^2 ($\sim 300\text{g/in}^2$)
- Brazing Cycle:
 - 15°C/min to 975°C , soak 10 minutes;
 - 10°C/min to T_{PEAK}^* , soak t_{PEAK}^{**} minutes;
 - 25°C/min to 975°C , soak 0 minutes;
 - 15°C/min to ambient.

* $T_{\text{PEAK}} = 1025^\circ\text{C}, 1030^\circ\text{C}, 1035^\circ\text{C}$ or 1055°C ; ** $t_{\text{PEAK}} = 1$ or 2 minutes



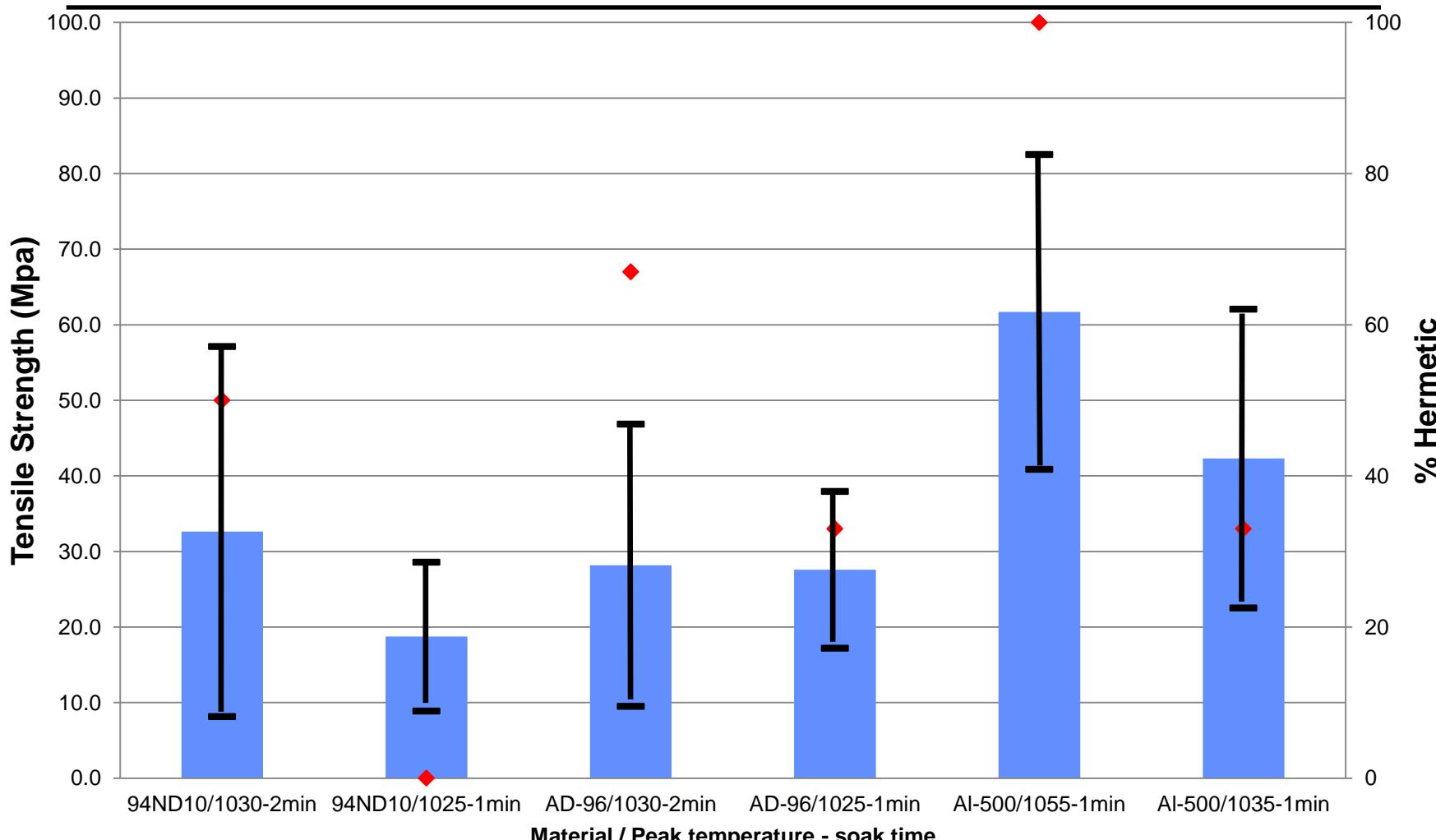
Experimental trials – sample results

Ceramic Substrate	Peak Temp	Peak Time	Helium Leak Test Results (Ratio Passing*/Total)	Avg. Tensile Strength (psi)
94% alumina	1030°C	2 min.	3 / 6	34.2 \pm 24.5 Mpa (4732)
94% alumina	1025°C	1 min.	0 / 6	18.7 \pm 9.8 MPa (2717)
96% alumina	1030°C	2 min.	4 / 6	28.2 \pm 18.7 MPa (4088)
96% alumina	1025°C	1 min.	2 / 6	27.6 \pm 10.4 MPa (4000)
95% alumina metallized	1055°C	1 min.	6 / 6	61.7 \pm 20.8 MPa (8947)
95% alumina metallized	1035°C	1 min.	2 / 6	42.3 \pm 19.8 MPa (6135)

*Passing = leak rates \leq 5.0E-012 atm-cc/sec or NDL.

Brazed Tensile Strength ASTM-F19 Tensile Buttons with explosively bonded Nb-Cu interlayers

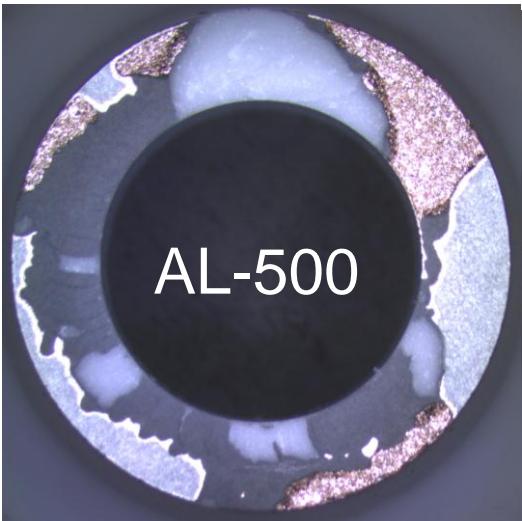
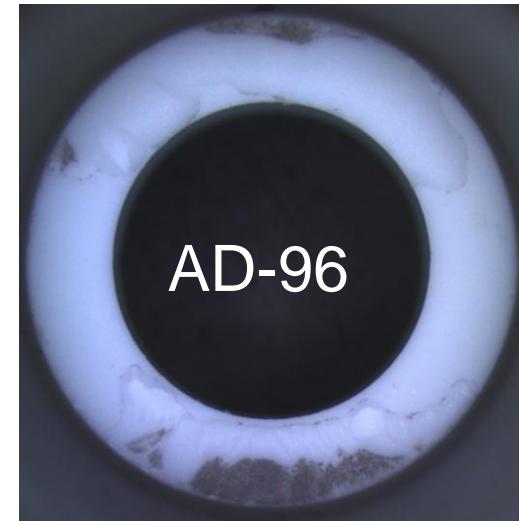
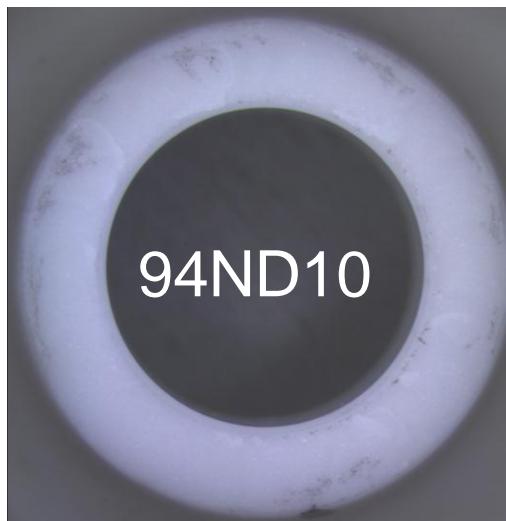
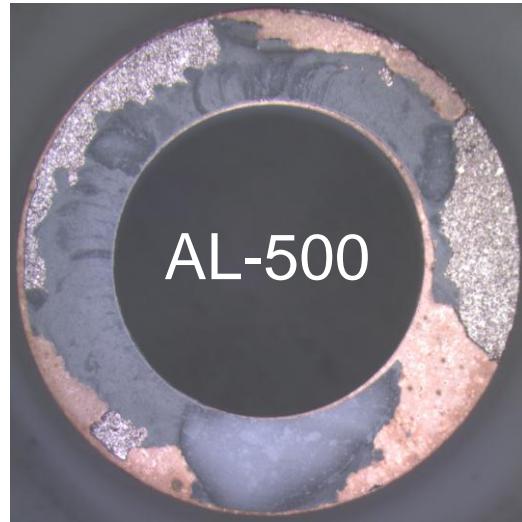
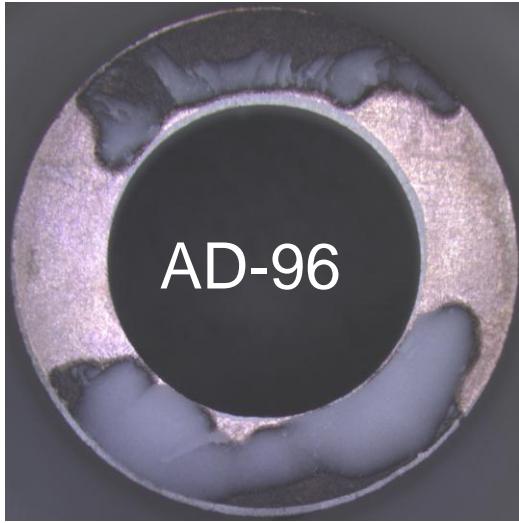
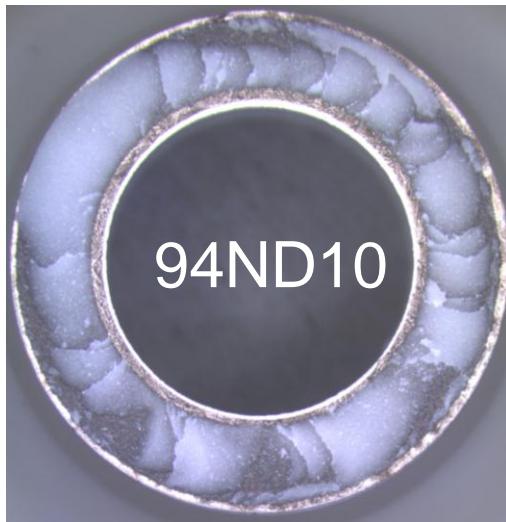
★ 120 MPa



■ Average Strength - +1sd - -1sd ◆ % hermetic

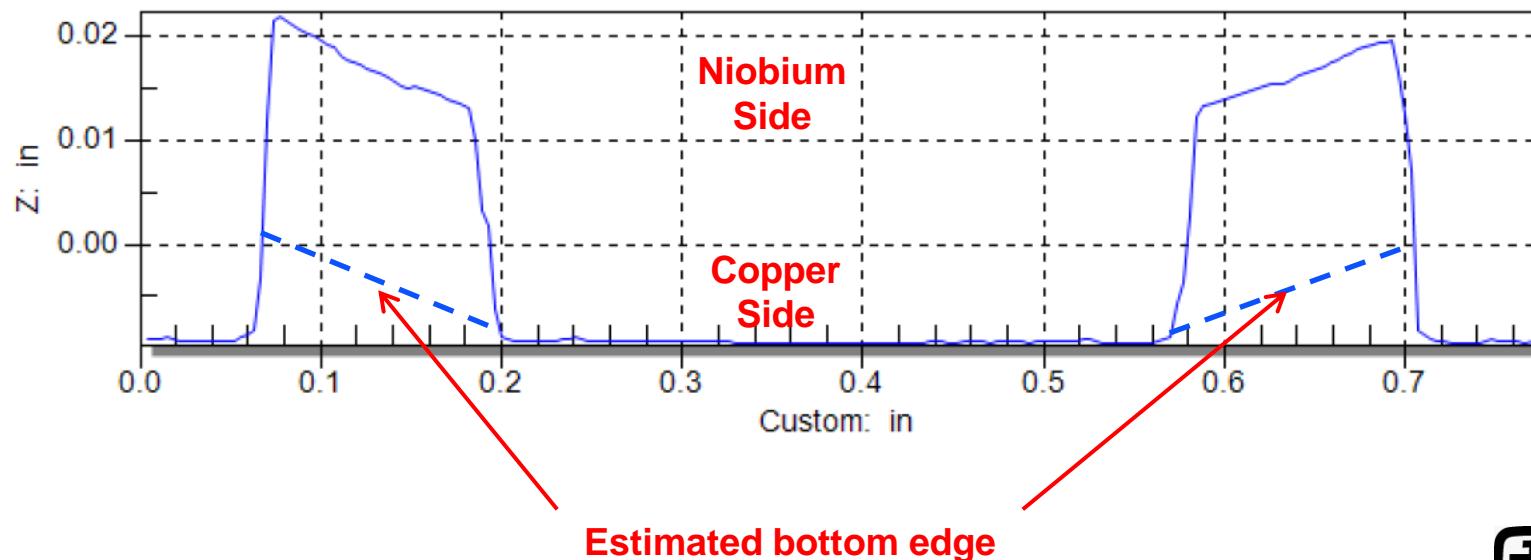
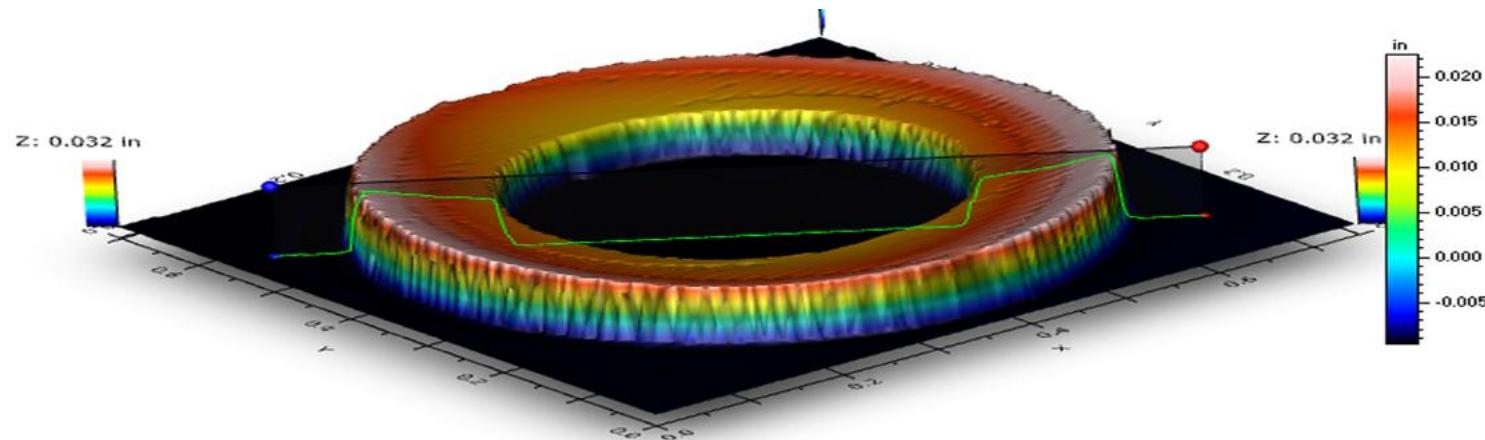


Observed brazed joint failures





Measured Nb-Cu interlayer flatness following thermal cycle





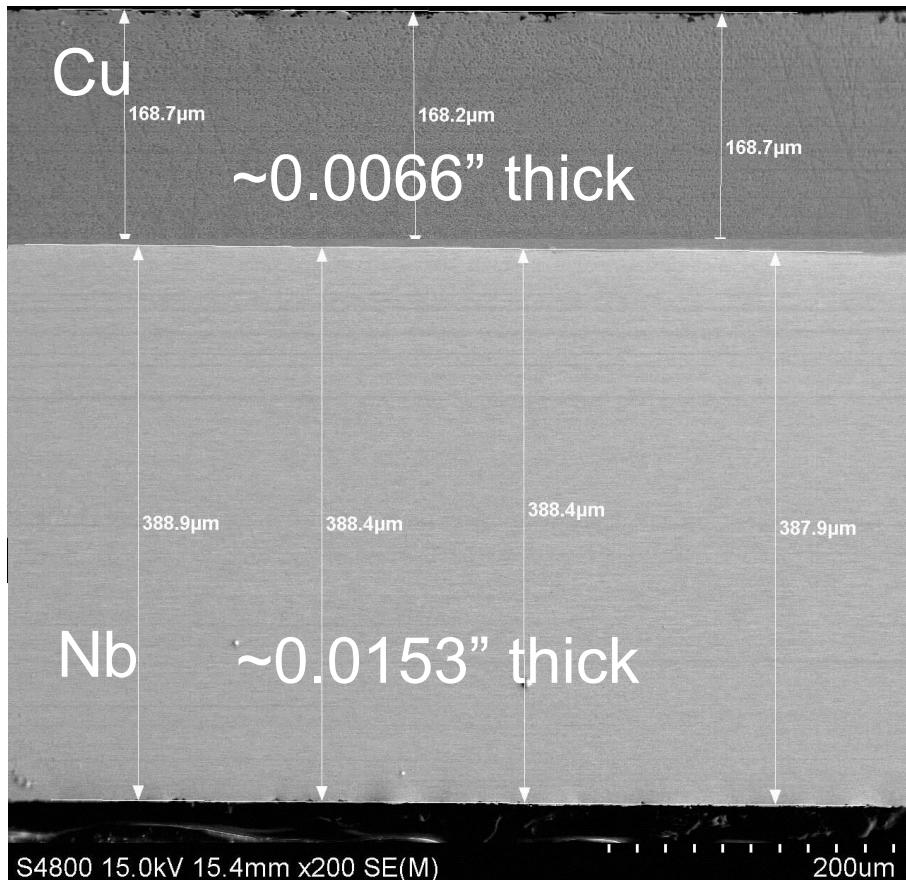
Proposed “cupping” mechanism

Niobium & Copper Selected Material Properties

	Niobium, Cold- worked	Niobium, Annealed	Copper, Cold-worked	Copper, Annealed
UTS (MPa/ksi) ¹ = 1000°C, ² = 600°C	600 / 87.0	300 / 43.5 90-120 / 13-17 ¹	344 / 49.9	210 / 30.5 10 / 1.5 ²
CTE , linear 0-1000°C (in/in-°C)	8.5	8.5	24.8	24.8
Melting Pt. (°C)	2468	2468	1084	1084
Anneal Temp* (°C) *1/2 – 1/3 Abs mp (K)	1100 - 1550	1100 - 1550	400 - 630	400 - 630



Cupping mechanism - continued



Cold-worked (high stress)
Nb-Cu substrate at room
temperature

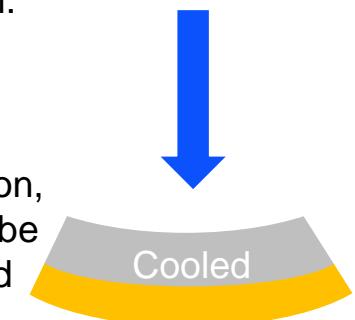
Low CTE
High CTE

1060°C-10 minutes,
800°C – 180 minutes

Nb warps as some internal
stresses are relieved.

The much weaker Cu yields to the
thicker, stronger Nb material.

Though under compression,
Nb remains too strong to be
deformed by the annealed
Cu...cup shape remains.



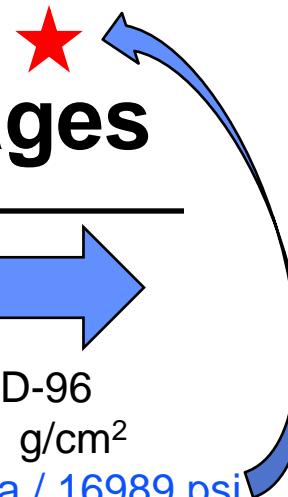


Experimental trials (round 2)

– additional joint preload sample results

Ceramic Substrate	Peak Temp	Peak Time	Joint Preload (g/in ²)	Helium Leak Test Results (Ratio Passing*/Total)	Tensile Strength (psi)
96% alumina	1055 ^o C	2 min.	101 g/cm ² (653)	0/1	34.2 Mpa (4961)
96% alumina	1055 ^o C	2 min.	188 g/cm ² (1212)	1/1	85.8 MPa (12447)
96% alumina	1050 ^o C	2 min.	275 g/cm ² (1771)	1/1	52.3 MPa (7581)
96% alumina	1055 ^o C	2 min.	361 g/cm ² (2329)	1/1	117.1 MPa (16989) Expected with this material set

*Passing = leak rates \leq 5.0E-012 atm-cc/sec or NDL.



Increased joint preload failure images

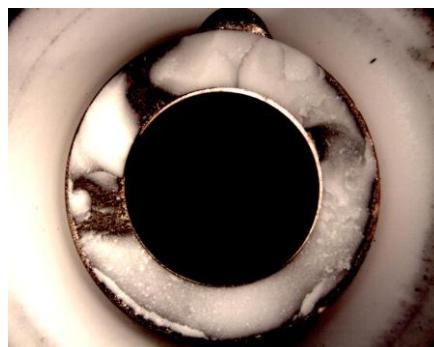
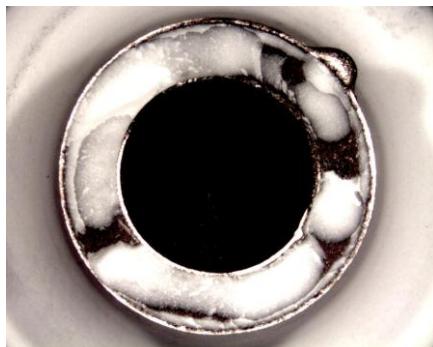
Increasing joint preload = increased tensile strength

AD-96
101 g/cm²
34.2 Mpa / 4961psi

AD-96
188 g/cm²
85.8 Mpa / 12447 psi

AD-96
275 g/cm²
52.3 Mpa / 7581 psi

AD-96
361 g/cm²
117.1 Mpa / 16989 psi





Conclusion & path forward

Conclusion

Residual stress in the explosively bonded Nb-Cu substrates is relieved during heating cycle resulting in excessive warp.

Additional joint preload to increase effective joint area greatly increases sample tensile strength.

Mass required to completely “flatten” substrates not practical for brazing manufacturing process.

Fully functional switches have been brazed/solder-dipped (SAC- 305) using the smaller bonded substrates.

Path forward

Investigate alternative manufacturing methods

- Diffusion-bonding
- Cold-spraying
- Rolling/forming operation modifications

Perform additional characterization of braze joints.



Acknowledgements

- **Tom Crenshaw** – Mechanical properties testing
- **Randy Herrick** – SEM analysis
- **David Saiz** – OGP & measurements
- **Lynna Esquibel** – Measurements

(All Sandia National Laboratories, NM)



The End

Thank you!

Questions?